

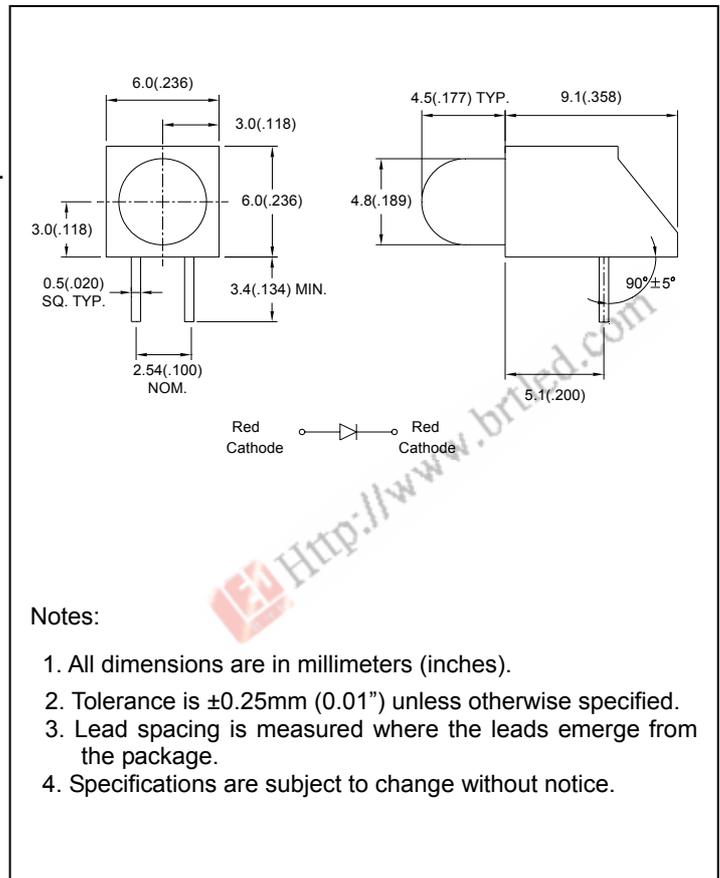
● Features:

1. Chip material: GaP/GaP
2. Emitted color : Bright Red
3. Lens Appearance : Red Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. This product don't contained restriction substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions:



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25\text{mm}$ (0.01") unless otherwise specified.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

● Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_d	40	mW
Forward Current	I_F	15	mA
Peak Forward Current* ¹	I_{FP}	50	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	$-40^\circ\text{C} \sim 85^\circ\text{C}$	
Storage Temperature	T_{stg}	$-40^\circ\text{C} \sim 100^\circ\text{C}$	
Soldering Temperature	T_{sol}	260°C max (for 5 seconds)	
Hand Soldering Temperature	T_{sol}	350°C max (for 3 seconds)	

*¹Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20mA$	-	2.3	2.6	V
Luminous Intensity	I_v	$I_F=20mA$	-	3.0	-	mcd
Reverse Current	I_R	$V_R=5V$	-	-	100	μA
Peak Wave Length	λ_p	$I_F=20mA$	-	700	-	nm
Dominant Wave Length	λ_d	$I_F=20mA$	-	650	-	nm
Spectral Line Half-width	$\Delta \lambda$	$I_F=20mA$	-	100	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20mA$	-	45	-	deg

● Typical electro-optical characteristics curves

Fig.1 Relative intensity vs. Wavelength

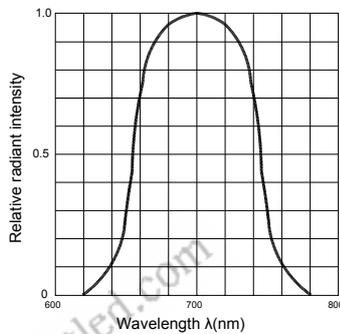


Fig.2 Forward current derating curve vs. Ambient temperature

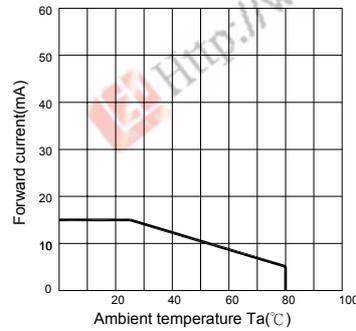


Fig.3 Forward current vs. Forward voltage

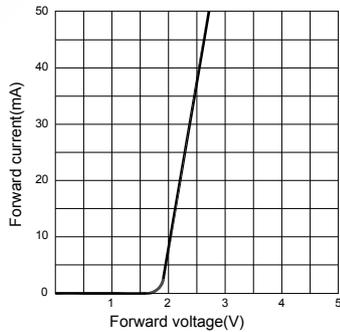


Fig.4 Relative luminous intensity vs. Ambient temperature

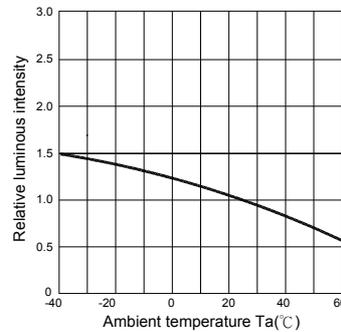


Fig.5 Relative luminous intensity vs. Forward current

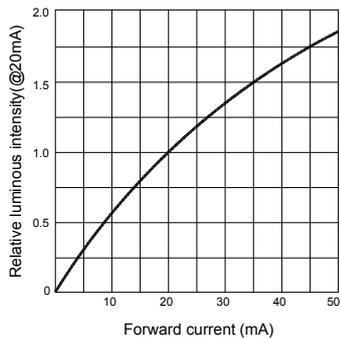
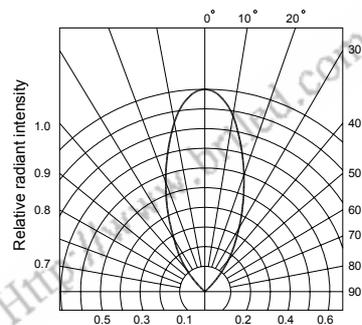


Fig.6 Radiation diagram



●DIP soldering (Wave Soldering)

Preheating : 120°C ,within 120~180 sec.

Operation heating : 255°C±5°C within 5 sec.260°C (Max)

Gradual Cooling (Avoid quenching).

